



Spec No.: DS70-2001-004 Effective Date: 10/27/2016

Revision: L

LITE-ON DCC

RELEASE

BNS-OD-FC001/A4



1. DESCRIPTION

1.1 Features

- AC input response
- \blacksquare Current transfer ratio (CTR : MIN. 20% at I_F = ± 1 mA, V_{CE} = 5V)
- Current transfer ratio (CTR : 50% to 300% at $I_F = \pm 5$ mA, $V_{CE} = 5$ V)
- High input-output isolation voltage (V_{iso} = 3,750Vrms)
- Mini-flat package : 2.0mm profile : LTV-354T series
- Safety approval

UL 1577 & cUL

VDE DIN EN60747-5-5 (VDE 0884-5),

CSA CA5A

CQC GB4943.1-2011/ GB8898-2011

FIMKO/DEMKO/SEMKO/NEMKO

- RoHS Compliance
 - All materials be used in device are followed EU RoHS directive (No.2002/95/EC).
- ESD pass HBM 8000V/ MM2000V /CDM2000V
- MSL class1

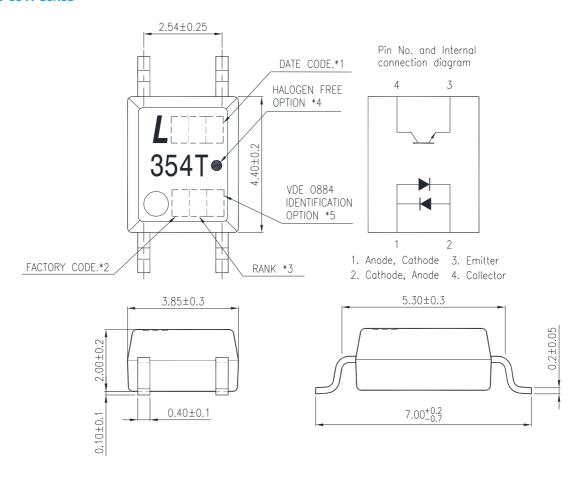
1.2 Applications

- Hybrid substrates that require high density mounting.
- Programmable controllers
- System appliance, measuring instruments



2. PACKAGE DIMENSIONS

2.1 LTV-354T series



Notes:

- 1. 1-digit year code, Example : 2010 = A 2-digit work week ranging from '01' to '53'
- 2. Factory identification mark shall be marked (W: China -CZ, X: China -TJ)
- 3. Rank shall be or shall not be marked.
- 4. "•" indicates halogen free option.
- 5. "4"or"V" for VDE option.

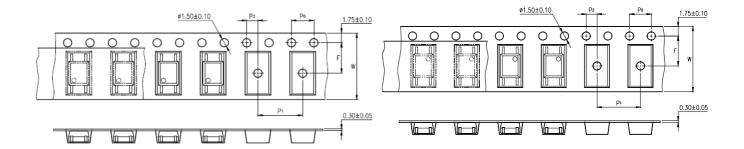
^{*}All dimensions in millimeters.



3. TAPING DIMENSIONS

3.1 LTV-354T-TP

3.2 LTV-354T-TP1



Description	Symbol	Dimension in mm (inch)
Tape wide	W	12±0.3 (0.472)
Pitch of sprocket holes	P ₀	4±0.1 (0.157)
Distance of compartment	F	5.5±0.1 (0.217)
Distance of compartment	P_2	2±0.1 (0.079)
Distance of compartment to compartment	P ₁	8±0.1 (0.315)

3.3 Quantities Per Reel

Package Type	LTV-354T series
Quantities (pcs)	3000



4. RATING AND CHARACTERISTICS

4.1 Absolute Maximum Ratings at Ta=25°C

	Parameter	Symbol	Rating	Unit
	Forward Current	l _F	±50	mA
Input	Power Dissipation	Р	70	mW
	Junction Temperature	Τ _J	125	°C
	Collector - Emitter Voltage	V_{CEO}	35	V
	Emitter - Collector Voltage	V _{ECO}	6	V
Output	Collector Current	Ic	50	mA
	Collector Power Dissipation		150	mW
	Junction Temperature	ΤJ	125	°C
	Total Power Dissipation	P _{tot}	170	mW
1.	Isolation Voltage	V _{iso}	3750	V_{rms}
	Operating Temperature	T_{opr}	-55 ~ +110	°C
	Storage Temperature	T_{stg}	-55 ~ +150	°C
2.	Soldering Temperature	T _{sol}	260	°C

1. AC For 1 Minute, R.H. = 40 ~ 60%

Isolation voltage shall be measured using the following method.

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
- (2) The isolation voltage tester with zero-cross circuit shall be used.
- (3) The waveform of applied voltage shall be a sine wave.
- 2. For 10 Seconds



4.2 ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C

	Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Input _	Forward Voltage	V _F	_	1.2	1.4	٧	I _F =±20mA
	Terminal Capacitance	Ct	_	30	250	pF	V=0, f=1KHz
	Collector Dark Current	I _{CEO}	_	_	100	nA	V _{CE} =20V, I _F =0
Output	Collector-Emitter Breakdown Voltage	BV _{CEO}	35	_	_	V	I _C =0.1mA, I _F =0
	Emitter-Collector Breakdown Voltage	BV _{ECO}	6	_	—	V	I _E =10μΑ, I _F =0
	Collector-Emitter Saturation Voltage	V _{CE(sat)}	_	0.1	0.2	V	I _F =±20mA I _C =1mA
	Isolation Resistance	R_{iso}	5×10 ¹⁰	1×10 ¹¹	_	Ω	DC500V, 40 ~ 60% R.H.
	Floating Capacitance	Cf	_	0.6	1	pF	V=0, f=1MHz
	Response Time (Rise)	tr	_	4	18	μs	V _{CE} =2V, I _C =2mA
	Response Time (Fall)	tf	_	3	18	μs	$R_L=100\Omega$,



5. RANK TABLE OF CURRENT TRANSFER RATIO (CTR)

CTR Rank	Min	Max	Condition
GR	50	300	I _F =±5mA, V _{CE} =5V, Ta=25°C
А	50	150	
В	80	400	
B2	100	400	I _F =±1mA, V _{CE} =5V, Ta=25°C
С	200	400	
No mark	20	400	

$$CTR = \frac{I_C}{I_F} \times 100\%$$



6. CHARACTERISTICS CURVES (TYPICAL PERFORMANCE)

Fig.1 Forward Current vs.

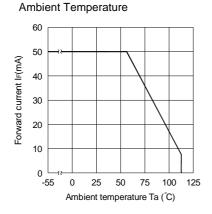


Fig.2 Collector Power Dissipation vs.
Ambient Temperature

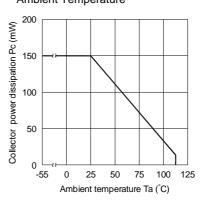


Fig.3 Collector-emitter Saturation Voltage vs. Forward Current

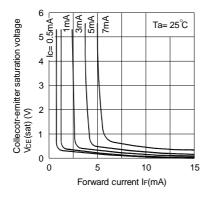


Fig.4 Forward Current vs. Forward Voltage

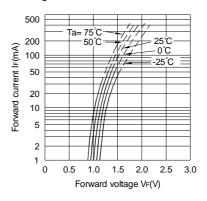


Fig.5 Current Transfer Ratio vs.
Forward Current

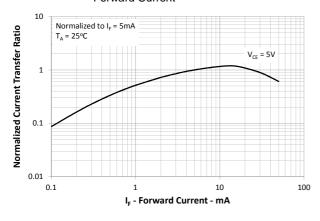


Fig.6 Collector Current vs.

Collector-emitter Voltage

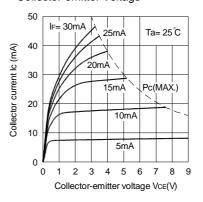
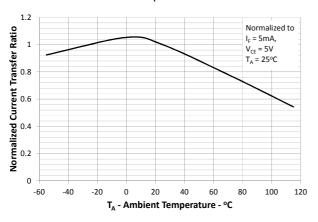




Fig.7 Relative Current Transfer Ratio vs. Ambient Temperature



vs. Ambient Temperature

Fig.8 Collector-emitter Saturation Voltage

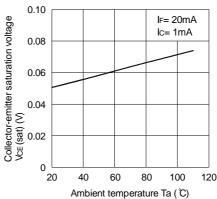


Fig.9 Collector Dark Current vs.
Ambient Temperature

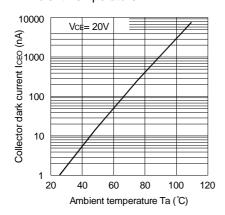


Fig.10 Response Time vs. Load Resistance

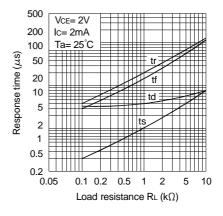
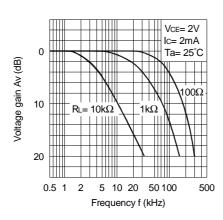
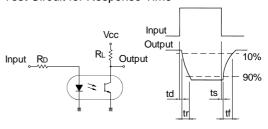


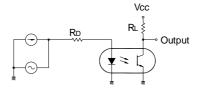
Fig.11 Frequency Response



Test Circuit for Response Time



Test Circuit for Frequency Response



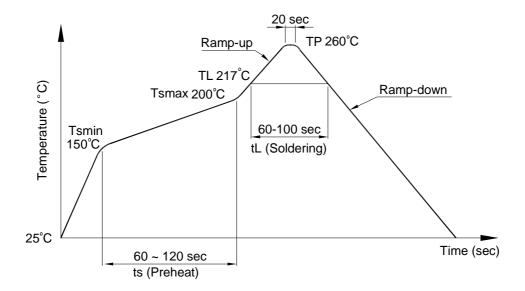


7. TEMPERATURE PROFILE OF SOLDERING

7.1 IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

Profile item	Conditions	
Preheat		
- Temperature Min (T _{Smin})	150°C	
- Temperature Max (T _{Smax})	200°C	
- Time (min to max) (ts)	90±30 sec	
Soldering zone		
- Temperature (T _L)	217°C	
- Time (t∟)	60 ~ 100 sec	
Peak Temperature (T _P)	260°C	
Ramp-up rate	3°C / sec max.	
Ramp-down rate	3~6°C / sec	





7.2 Wave soldering (JEDEC22A111 compliant)

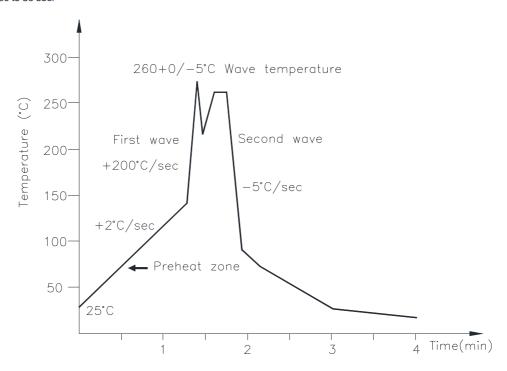
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C

Time: 10 sec.

Preheat temperature:25 to 140°C

Preheat time: 30 to 80 sec.



7.3 Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

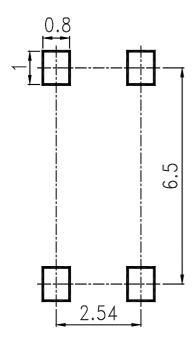
Temperature: 380+0/-5°C

Time: 3 sec max.



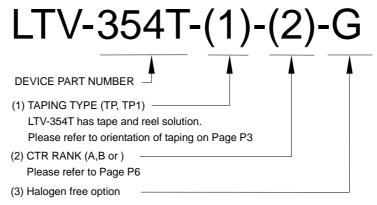
8. RRECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)

Unit: mm

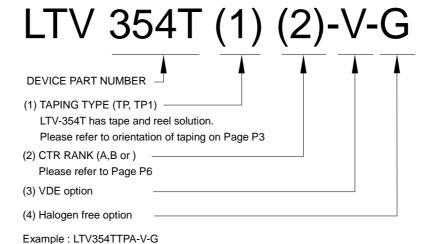




9. NAMING RULE



Example: LTV-354T-TP-A-G



10. NOTES

- LiteOn is continually improving the quality, reliability, function or design and LiteOn reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.
- The contents described herein are subject to change without prior notice.
- Immerge unit's body in solder paste is not recommended.